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CONTENTS

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## PAGE REGULAR ISSUE PAPERS

- 247 Fabrication of Metal-Oxide-Diamond Field-Effect Transistors with Submicron-Sized Gate Length on Boron-Doped (111) H-Terminated Surfaces Using Electron Beam Evaporated  $\text{SiO}_2$  and  $\text{Al}_2\text{O}_3$   
*Takeyasu Saito, Kyung-ho Park, Kazuyuki Hirama, Hitoshi Umezawa, Mitsuya Satoh, Hiroshi Kawarada, Zhi-Quan Liu, Kazutaka Mitsuishi, Kazuo Furuya, and Hideyo Okushi*
- 253 Local Piezoelectricity and Polarity Distribution of Preferred *c*-Axis-Oriented ZnO Film Investigated by Piezoresponse Force Microscopy  
*Cui Ping Li and Bao He Yang*
- 259 Tailoring the Structural and Optoelectronic Properties of Al-Doped Nanocrystalline ZnO Thin Films  
*C. Periasamy and P. Chakrabarti*
- 267 The Influence of Film Thickness on the Transparency and Conductivity of Al-Doped ZnO Thin Films Fabricated by Ion-Beam Sputtering  
*Guang-Xing Liang, Ping Fan, Xing-Min Cai, Dong-Ping Zhang, and Zhuang-Hao Zheng*
- 274 Point Defects in CdZnTe Crystals Grown by Different Techniques  
*R. Gul, A. Bolotnikov, H.K. Kim, R. Rodriguez, K. Keeter, Z. Li, G. Gu, and R.B. James*
- 280 The Distribution Tail of LWIR HgCdTe-on-Si FPAs: a Hypothetical Physical Mechanism  
*L.O. Bubulac, J.D. Benson, R.N. Jacobs, A.J. Stoltz, M. Jaime-Vasquez, L.A. Almeida, A. Wang, L. Wang, R. Hellmer, T. Golding, J.H. Dinan, M. Carmody, P.S. Wijewarnasuriya, M.F. Lee, M.F. Vilela, J. Peterson, S.M. Johnson, D.F. Lofgreen, and D. Rhiger*
- 289 Study of the Formation Mechanism of Cu/Ge/Pd Ohmic Contact to *n*-Type InGaAs  
*Y.C. Lin, Sheng-Li Shie, Tin-En Shie, Yuen-Yee Wong, K.S. Chen, and E.Y. Chang*
- 295 Electrical Conductivity of Parylene F at High Temperature  
*S. Diahm, M. Bechara, M.-L. Locatelli, and C. Tenaillon*
- 301 Laser Direct Writing of Conductive Silver Film on Polyimide Surface from Decomposition of Organometallic Ink  
*Zhixiang Cai, Xiaoyan Zeng, and Jianguo Liu*

Contents continued on A9

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- 306 Interfacial Reactions of Sn-3.5Ag-xZn Solders and Cu Substrate During Liquid-State Aging  
*Lijuan Liu, Wei Zhou, Wenkai Mu, and Ping Wu*
- 315 Mechanical Properties and Electrochemical Corrosion Behavior of Al/Sn-9Zn-xAg/Cu Joints  
*M.L. Huang, Y.Z. Huang, H.T. Ma, and J. Zhao*
- 324 Effects of Bonding Temperature and Pressure on the Electrical Resistance of Cu/Sn/Cu Joints for 3D Integration Applications  
*Byunghoon Lee, Jongseo Park, Junghyun Song, Kee-won Kwon, and Hoo-jeong Lee*
- 330 An Investigation of Diffusion Barrier Characteristics of an Electroless Co(W,P) Layer to Lead-Free SnBi Solder  
*Hung-Chun Pan and Tsung-Eong Hsieh*
- 340 Preparation of  $\text{Bi}_{0.85}\text{Nd}_{0.15}\text{FeO}_3$  Nanotube Arrays by a Sol-Gel Template Method  
*Dongyun Guo, Yiping Gong, Changyong Liu, Chuanbin Wang, Qiang Shen, and Lianmeng Zhang*
- 344 Creep Properties of Sn-1.0Ag-0.5Cu Lead-Free Solder with Ni Addition  
*F.X. Che, W.H. Zhu, Edith S.W. Poh, X.R. Zhang, Xiaowu Zhang, T.C. Chai, and S. Gao*
- 355 Dielectric Properties and Microstructure of MgO-TiO<sub>2</sub>-ZnO-CaO Ceramics  
*Yonggang Zhang, Shunhua Wu, Jinxu Liu, and Shunqi Gao*